

L	Hits	Search Text	DB	Time stamp
Number				
_	434	(carrier interposer) and power and ground	USPAT;	2002/11/16
		and (conductive adj adhesive) and	US-PGPUB;	23:23
		@ad<19990719	EPO; JPO;	
		•	DERWENT;	
			IBM TDB	
	330	((carrier interposer) and power and	USPAT;	2002/11/16
		ground and (conductive adj adhesive) and	US-PGPUB;	23:23
		(@ad<19990719) and substrate	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	. 29	(carrier interposer) and power and ground	USPAT;	2002/11/16
		and (conductive adj adhesive adj layer)	US-PGPUB;	23:25
		and @ad<19990719	EPO; JPO;	
		and cad (1999)	DERWENT;	1
			IBM TDB	
-	23	((carrier interposer) and power and	USPAT;	2002/11/16
	25	ground and (conductive adj adhesive adj	US-PGPUB;	23:25
		layer) and @ad<19990719) and signal	EPO; JPO;	
		layer, and caderissionis, and signar	DERWENT;	
			TRM TDB	